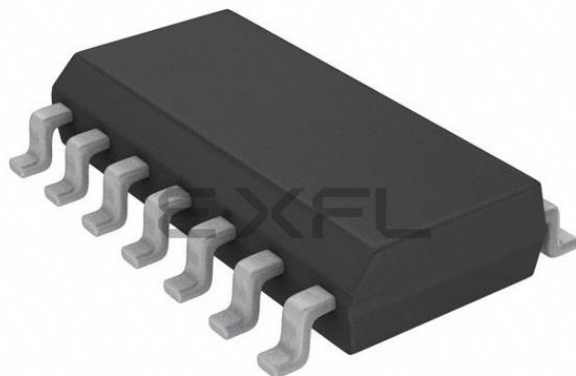




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Details

Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	32MHz
Connectivity	I ² C, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	12
Program Memory Size	7KB (4K x 14)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	512 x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 8x10b; D/A 1x8b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	14-SOIC (0.154", 3.90mm Width)
Supplier Device Package	14-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lf1614t-i-sl

TABLE 3-14: SPECIAL FUNCTION REGISTER SUMMARY (CONTINUED)

Addr	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other Resets
Bank 1											
08Ch	TRISA	—	—	TRISA5	TRISA4	— ⁽²⁾	TRISA2	TRISA1	TRISA0	--11 1111	--11 1111
08Dh	TRISB ⁽⁴⁾	TRISB7	TRISB6	TRISB5	TRISB4	—	—	—	—	1111 ----	1111 ----
08Eh	TRISC	TRISC7 ⁽⁴⁾	TRISC6 ⁽⁴⁾	TRISC5	TRISC4	TRISC3	TRISC2	TRISC1	TRISC0	1111 1111	1111 1111
08Fh	—	Unimplemented								—	—
090h	—	Unimplemented								—	—
090h	PIE1	TMR1GIE	ADIE	RCIE	TXIE	SSP1IE	CCP1IE	TMR2IE	TMR1IE	0000 0000	0000 0000
091h	PIE2	—	C2IE	C1IE	—	BCLIE	TMR6IE	TMR4IE	CCP2IE	-00- 0000	-00- 0000
092h	PIE3	—	—	CWGIE	ZCDIE	—	—	CLC2IE	CLC1IE	--00 --00	--00 --00
093h	PIE4	SCANIE	CRCIE	SMT2PWAIE	SMT2PRAIE	SMT2IE	SMT1PWAIE	SMT1PRAIE	SMT1IE	0000 0000	0000 0000
094h	PIE5	TMR3GIE	TMR3IE	TMR5GIE	TMR5IE	—	AT1IE	PID1EIE	PID1DIE	0000 -000	0000 -000
095h	OPTION_REG	WPUEN	INTEDG	TMR0CS	TMR0SE	PSA	PS<2:0>			1111 1111	1111 1111
096h	PCON	STKOVF	STKUNF	WDTWV	RWD $\overline{T}$	RMCLR	R $\overline{I}$	POR	BOR	00-1 11qq	qq-q qqqu
097h	—	Unimplemented								—	—
098h	OSCTUNE	—	—	TUN<5:0>						--00 0000	--00 0000
099h	OSCCON	SPLLEN	IRCF<3:0>				—	SCS<1:0>		0011 1-00	0011 1-00
09Ah	OSCSTAT	—	PLL $\overline{R}$	—	HFIOFR	HFIOFL	MFIOFR	LFIOFR	HFIOFS	-0-0 0000	-q-q qqqq
09Bh	ADRESL	ADC Result Register Low								xxxx xxxx	uuuu uuuu
09Ch	ADRESH	ADC Result Register High								xxxx xxxx	uuuu uuuu
09Dh	ADCON0	—	CHS<4:0>					GO/ $\overline{DONE}$	ADON	-000 0000	-000 0000
09Eh	ADCON1	ADFM	ADCS<2:0>			—	—	ADPREF<1:0>		0000 --00	0000 --00
09Fh	ADCON2	TRIGSEL<4:0>					—	—	—	0000 0---	0000 0---

Legend: x = unknown, u = unchanged, q = value depends on condition, - = unimplemented, r = reserved. Shaded locations are unimplemented, read as '0'.

- Note** 1: PIC16F1614/8 only.
 2: Unimplemented, read as '1'.
 3: PIC16(L)F1614 only.
 4: PIC16(L)F1618 only.

5.0 OSCILLATOR MODULE

5.1 Overview

The oscillator module has a wide variety of clock sources and selection features that allow it to be used in a wide range of applications while maximizing performance and minimizing power consumption. Figure 5-1 illustrates a block diagram of the oscillator module.

Clock sources can be supplied from external oscillators. In addition, the system clock source can be supplied from one of two internal oscillators and PLL circuits, with a choice of speeds selectable via software. Additional clock features include:

- Selectable system clock source between external or internal sources via software.

The oscillator module can be configured in one of the following clock modes.

1. ECL – External Clock Low-Power mode (0 MHz to 0.5 MHz)
2. ECM – External Clock Medium-Power mode (0.5 MHz to 4 MHz)
3. ECH – External Clock High-Power mode (4 MHz to 32 MHz)
4. INTOSC – Internal oscillator (31 kHz to 32 MHz).

Clock Source modes are selected by the FOSC<1:0> bits in the Configuration Words. The FOSC bits determine the type of oscillator that will be used when the device is first powered.

The ECH, ECM, and ECL Clock modes rely on an external logic level signal as the device clock source.

The INTOSC internal oscillator block produces low, medium, and high-frequency clock sources, designated LFINTOSC, MFINTOSC and HFINTOSC. (see Internal Oscillator Block, Figure 5-1). A wide selection of device clock frequencies may be derived from these three clock sources.

5.2.2.7 32 MHz Internal Oscillator Frequency Selection

The Internal Oscillator Block can be used with the 4x PLL associated with the External Oscillator Block to produce a 32 MHz internal system clock source. Either the 8 or 16 MHz internal oscillator settings can be used, with the 16 MHz being divided by two before being input into the PLL. The following settings are required to use the 32 MHz internal clock source:

- The FOSC bits in Configuration Words must be set to use the INTOSC source as the device system clock (FOSC<1:0> = 00).
- The SCS bits in the OSCCON register must be cleared to use the clock determined by FOSC<1:0> in Configuration Words (SCS<1:0> = 00).
- The IRCF bits in the OSCCON register must be set to either the 16 MHz (IRCF<3:0> = 1111) or the 8 MHz HFINTOSC (IRCF<3:0> = 1110).
- The SPLLEN bit in the OSCCON register must be set to enable the 4x PLL, or the PLEN bit of the Configuration Words must be programmed to a '1'.

Note: When using the PLEN bit of the Configuration Words, the 4x PLL cannot be disabled by software and the 8/16 MHz HFINTOSC option will no longer be available.

The 4x PLL is not available for use with the internal oscillator when the SCS bits of the OSCCON register are set to '1x'. The SCS bits must be set to '00' to use the 4x PLL with the internal oscillator.

5.2.2.8 Internal Oscillator Clock Switch Timing

When switching between the HFINTOSC, MFINTOSC and the LFINTOSC, the new oscillator may already be shut down to save power (see Figure 5-3). If this is the case, there is a delay after the IRCF<3:0> bits of the OSCCON register are modified before the frequency selection takes place. The OSCSTAT register will reflect the current active status of the HFINTOSC, MFINTOSC and LFINTOSC oscillators. The sequence of a frequency selection is as follows:

1. IRCF<3:0> bits of the OSCCON register are modified.
2. If the new clock is shut down, a clock start-up delay is started.
3. Clock switch circuitry waits for a falling edge of the current clock.
4. The current clock is held low and the clock switch circuitry waits for a rising edge in the new clock.
5. The new clock is now active.
6. The OSCSTAT register is updated as required.
7. Clock switch is complete.

See Figure 5-3 for more details.

If the internal oscillator speed is switched between two clocks of the same source, there is no start-up delay before the new frequency is selected. Clock switching time delays are shown in Table 5-1.

Start-up delay specifications are located in the oscillator tables of **Section 35.0 "Electrical Specifications"**.

6.1 Power-On Reset (POR)

The POR circuit holds the device in Reset until VDD has reached an acceptable level for minimum operation. Slow rising VDD, fast operating speeds or analog performance may require greater than minimum VDD. The PWRT, BOR or MCLR features can be used to extend the start-up period until all device operation conditions have been met.

6.1.1 POWER-UP TIMER (PWRT)

The Power-up Timer provides a nominal 64 ms time-out on POR or Brown-out Reset.

The device is held in Reset as long as PWRT is active. The PWRT delay allows additional time for the VDD to rise to an acceptable level. The Power-up Timer is enabled by clearing the PWRT bit in Configuration Words.

The Power-up Timer starts after the release of the POR and BOR.

For additional information, refer to Application Note AN607, "Power-up Trouble Shooting" (DS00607).

6.2 Brown-Out Reset (BOR)

The BOR circuit holds the device in Reset when VDD reaches a selectable minimum level. Between the POR and BOR, complete voltage range coverage for execution protection can be implemented.

The Brown-out Reset module has four operating modes controlled by the BOREN<1:0> bits in Configuration Words. The four operating modes are:

- BOR is always on
- BOR is off when in Sleep
- BOR is controlled by software
- BOR is always off

Refer to Table 6-1 for more information.

The Brown-out Reset voltage level is selectable by configuring the BORV bit in Configuration Words.

A VDD noise rejection filter prevents the BOR from triggering on small events. If VDD falls below VBOR for a duration greater than parameter TBORDC, the device will reset. See Figure 6-2 for more information.

TABLE 6-1: BOR OPERATING MODES

BOREN<1:0>	SBOREN	Device Mode	BOR Mode	Instruction Execution upon: Release of POR or Wake-up from Sleep
11	X	X	Active	Waits for BOR ready ⁽¹⁾ (BORRDY = 1)
10	X	Awake	Active	Waits for BOR ready (BORRDY = 1)
		Sleep	Disabled	
01	1	X	Active	Waits for BOR ready ⁽¹⁾ (BORRDY = 1)
	0	X	Disabled	Begins immediately (BORRDY = x)
00	X	X	Disabled	

Note 1: In these specific cases, "release of POR" and "wake-up from Sleep," there is no delay in start-up. The BOR ready flag, (BORRDY = 1), will be set before the CPU is ready to execute instructions because the BOR circuit is forced on by the BOREN<1:0> bits.

6.2.1 BOR IS ALWAYS ON

When the BOREN bits of Configuration Words are programmed to '11', the BOR is always on. The device start-up will be delayed until the BOR is ready and VDD is higher than the BOR threshold.

BOR protection is active during Sleep. The BOR does not delay wake-up from Sleep.

6.2.2 BOR IS OFF IN SLEEP

When the BOREN bits of Configuration Words are programmed to '10', the BOR is on, except in Sleep. The device start-up will be delayed until the BOR is ready and VDD is higher than the BOR threshold.

BOR protection is not active during Sleep. The device wake-up will be delayed until the BOR is ready.

6.2.3 BOR CONTROLLED BY SOFTWARE

When the BOREN bits of Configuration Words are programmed to '01', the BOR is controlled by the SBOREN bit of the BORCON register. The device start-up is not delayed by the BOR ready condition or the VDD level.

BOR protection begins as soon as the BOR circuit is ready. The status of the BOR circuit is reflected in the BORRDY bit of the BORCON register.

BOR protection is unchanged by Sleep.

8.0 POWER-DOWN MODE (SLEEP)

The Power-Down mode is entered by executing a SLEEP instruction.

Upon entering Sleep mode, the following conditions exist:

1. WDT will be cleared but keeps running, if enabled for operation during Sleep.
2. $\overline{PD}$ bit of the STATUS register is cleared.
3. $\overline{TO}$ bit of the STATUS register is set.
4. CPU clock is disabled.
5. 31 kHz LFINTOSC is unaffected and peripherals that operate from it may continue operation in Sleep.
6. Timer1 and peripherals that operate from Timer1 continue operation in Sleep when the Timer1 clock source selected is:
 - LFINTOSC
 - T1CKI
 - Timer1 oscillator
7. ADC is unaffected, if the dedicated FRC oscillator is selected.
8. I/O ports maintain the status they had before SLEEP was executed (driving high, low or high-impedance).
9. Resets other than WDT are not affected by Sleep mode.

Refer to individual chapters for more details on peripheral operation during Sleep.

To minimize current consumption, the following conditions should be considered:

- I/O pins should not be floating
- External circuitry sinking current from I/O pins
- Internal circuitry sourcing current from I/O pins
- Current draw from pins with internal weak pull-ups
- Modules using 31 kHz LFINTOSC
- CWG modules using HFINTOSC

I/O pins that are high-impedance inputs should be pulled to VDD or VSS externally to avoid switching currents caused by floating inputs.

Examples of internal circuitry that might be sourcing current include the FVR module. See **Section 15.0 “Fixed Voltage Reference (FVR)”** for more information on this module.

8.1 Wake-up from Sleep

The device can wake-up from Sleep through one of the following events:

1. External Reset input on $\overline{MCLR}$ pin, if enabled
2. BOR Reset, if enabled
3. POR Reset
4. Watchdog Timer, if enabled
5. Any external interrupt
6. Interrupts by peripherals capable of running during Sleep (see individual peripheral for more information)

The first three events will cause a device Reset. The last three events are considered a continuation of program execution. To determine whether a device Reset or wake-up event occurred, refer to **Section 6.12 “Determining the Cause of a Reset”**.

When the SLEEP instruction is being executed, the next instruction (PC + 1) is prefetched. For the device to wake-up through an interrupt event, the corresponding interrupt enable bit must be enabled. Wake-up will occur regardless of the state of the GIE bit. If the GIE bit is disabled, the device continues execution at the instruction after the SLEEP instruction. If the GIE bit is enabled, the device executes the instruction after the SLEEP instruction, the device will then call the Interrupt Service Routine. In cases where the execution of the instruction following SLEEP is not desirable, the user should have a NOP after the SLEEP instruction.

The WDT is cleared when the device wakes up from Sleep, regardless of the source of wake-up.

8.1.1 WAKE-UP USING INTERRUPTS

When global interrupts are disabled (GIE cleared) and any interrupt source has both its interrupt enable bit and interrupt flag bit set, one of the following will occur:

- If the interrupt occurs **before** the execution of a SLEEP instruction
 - SLEEP instruction will execute as a NOP
 - WDT and WDT prescaler will not be cleared
 - $\overline{TO}$ bit of the STATUS register will not be set
 - $\overline{PD}$ bit of the STATUS register will not be cleared
- If the interrupt occurs **during or after** the execution of a SLEEP instruction
 - SLEEP instruction will be completely executed
 - Device will immediately wake-up from Sleep
 - WDT and WDT prescaler will be cleared
 - $\overline{TO}$ bit of the STATUS register will be set
 - $\overline{PD}$ bit of the STATUS register will be cleared

Even if the flag bits were checked before executing a SLEEP instruction, it may be possible for flag bits to become set before the SLEEP instruction completes. To determine whether a SLEEP instruction executed, test the $\overline{PD}$ bit. If the $\overline{PD}$ bit is set, the SLEEP instruction was executed as a NOP.

REGISTER 22-2: T1GCON: TIMER1 GATE CONTROL REGISTER

R/W-0/u	R/W-0/u	R/W-0/u	R/W-0/u	R/W/HC-0/u	R-x/x	R/W-0/u	R/W-0/u
TMR1GE	T1GPOL	T1GTM	T1GSPM	T1GGO/ DONE	T1GVAL	T1GSS<1:0>	
bit 7							bit 0

Legend:

R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	HC = Bit is cleared by hardware

bit 7	TMR1GE: Timer1 Gate Enable bit If TMR1ON = 0 : This bit is ignored If TMR1ON = 1 : 1 = Timer1 counting is controlled by the Timer1 gate function 0 = Timer1 counts regardless of Timer1 gate function
bit 6	T1GPOL: Timer1 Gate Polarity bit 1 = Timer1 gate is active-high (Timer1 counts when gate is high) 0 = Timer1 gate is active-low (Timer1 counts when gate is low)
bit 5	T1GTM: Timer1 Gate Toggle Mode bit 1 = Timer1 Gate Toggle mode is enabled 0 = Timer1 Gate Toggle mode is disabled and toggle flip-flop is cleared Timer1 gate flip-flop toggles on every rising edge.
bit 4	T1GSPM: Timer1 Gate Single-Pulse Mode bit 1 = Timer1 gate Single-Pulse mode is enabled and is controlling Timer1 gate 0 = Timer1 gate Single-Pulse mode is disabled
bit 3	T1GGO/DONE: Timer1 Gate Single-Pulse Acquisition Status bit 1 = Timer1 gate single-pulse acquisition is ready, waiting for an edge 0 = Timer1 gate single-pulse acquisition has completed or has not been started
bit 2	T1GVAL: Timer1 Gate Value Status bit Indicates the current state of the Timer1 gate that could be provided to TMR1H:TMR1L. Unaffected by Timer1 Gate Enable (TMR1GE).
bit 0	T1GSS<1:0>: Timer1 Gate Source Select bits 11 = Comparator 2 optionally synchronized output (C2_OUT_sync) 10 = Comparator 1 optionally synchronized output (C1_OUT_sync) 01 = Timer0 overflow output (T0_overflow) 00 = Timer1 gate pin (T1G)

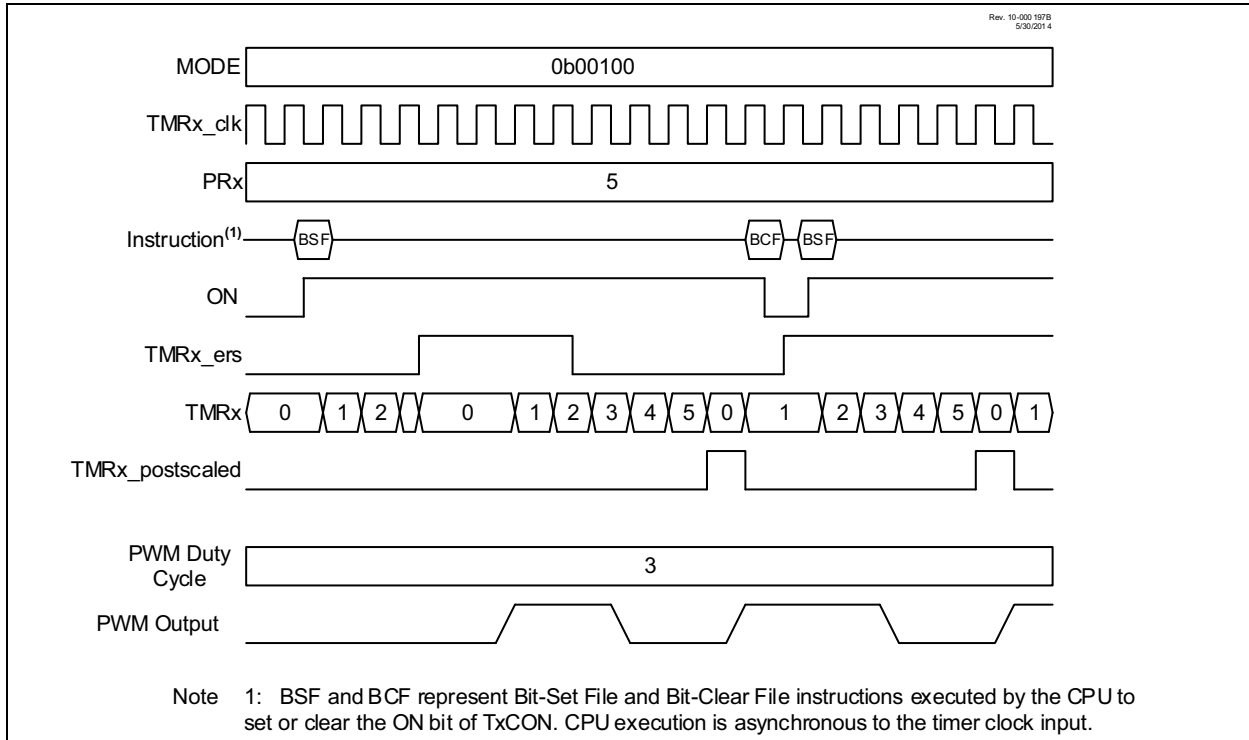
23.5.3 EDGE-TRIGGERED HARDWARE LIMIT MODE

In Hardware Limit mode the timer can be reset by the TMRx_ers external signal before the timer reaches the period count. Three types of Resets are possible:

- Reset on rising or falling edge (MODE<4:0>= 00011)
- Reset on rising edge (MODE<4:0> = 00100)
- Reset on falling edge (MODE<4:0> = 00101)

When the timer is used in conjunction with the CCP in PWM mode then an early Reset shortens the period and restarts the PWM pulse after a two-clock delay. Refer to Figure 23-6.

FIGURE 23-6: EDGE-TRIGGERED HARDWARE LIMIT MODE TIMING DIAGRAM (MODE = 00100)



23.5.8 LEVEL RESET, EDGE-TRIGGERED HARDWARE LIMIT ONE-SHOT MODES

In Level -Triggered One-Shot mode the timer count is reset on the external signal level and starts counting on the rising/falling edge of the transition from Reset level to the active level while the ON bit is set. Reset levels are selected as follows:

- Low Reset level (MODE<4:0> = 01110)
- High Reset level (MODE<4:0> = 01111)

When the timer count matches the PRx period count, the timer is reset and the ON bit is cleared. When the ON bit is cleared by either a PRx match or by software control a new external signal edge is required after the ON bit is set to start the counter.

When Level-Triggered Reset One-Shot mode is used in conjunction with the CCP PWM operation the PWM drive goes active with the external signal edge that starts the timer. The PWM drive goes inactive when the timer count equals the CCPRx pulse width count. The PWM drive does not go active when the timer count clears at the PRx period count match.

24.6.13.3 Bus Collision During a Stop Condition

Bus collision occurs during a Stop condition if:

- After the SDA pin has been deasserted and allowed to float high, SDA is sampled low after the BRG has timed out (Case 1).
- After the SCL pin is deasserted, SCL is sampled low before SDA goes high (Case 2).

The Stop condition begins with SDA asserted low. When SDA is sampled low, the SCL pin is allowed to float. When the pin is sampled high (clock arbitration), the Baud Rate Generator is loaded with SSPxADD and counts down to zero. After the BRG times out, SDA is sampled. If SDA is sampled low, a bus collision has occurred. This is due to another master attempting to drive a data '0' (Figure 24-38). If the SCL pin is sampled low before SDA is allowed to float high, a bus collision occurs. This is another case of another master attempting to drive a data '0' (Figure 24-39).

FIGURE 24-38: BUS COLLISION DURING A STOP CONDITION (CASE 1)

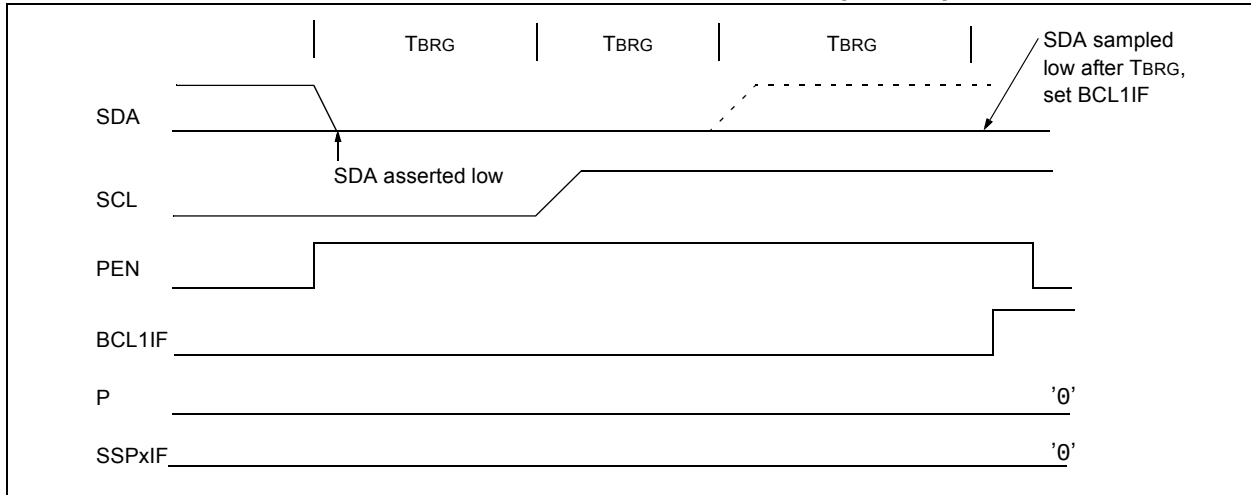
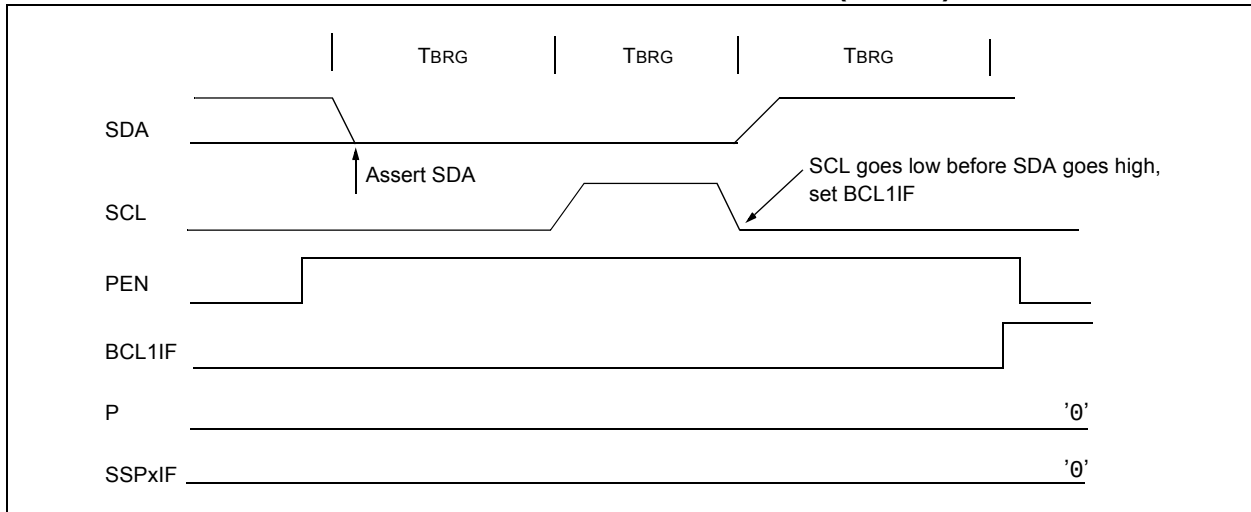


FIGURE 24-39: BUS COLLISION DURING A STOP CONDITION (CASE 2)



25.4.4 BREAK CHARACTER SEQUENCE

The EUSART module has the capability of sending the special Break character sequences that are required by the LIN bus standard. A Break character consists of a Start bit, followed by 12 '0' bits and a Stop bit.

To send a Break character, set the SENDB and TXEN bits of the TXxSTA register. The Break character transmission is then initiated by a write to the TXxREG. The value of data written to TXxREG will be ignored and all '0's will be transmitted.

The SENDB bit is automatically reset by hardware after the corresponding Stop bit is sent. This allows the user to preload the transmit FIFO with the next transmit byte following the Break character (typically, the Sync character in the LIN specification).

The TRMT bit of the TXxSTA register indicates when the transmit operation is active or idle, just as it does during normal transmission. See Figure 25-9 for the timing of the Break character sequence.

25.4.4.1 Break and Sync Transmit Sequence

The following sequence will start a message frame header made up of a Break, followed by an auto-baud Sync byte. This sequence is typical of a LIN bus master.

1. Configure the EUSART for the desired mode.
2. Set the TXEN and SENDB bits to enable the Break sequence.
3. Load the TXxREG with a dummy character to initiate transmission (the value is ignored).
4. Write '55h' to TXxREG to load the Sync character into the transmit FIFO buffer.
5. After the Break has been sent, the SENDB bit is reset by hardware and the Sync character is then transmitted.

When the TXxREG becomes empty, as indicated by the TXIF, the next data byte can be written to TXxREG.

25.4.5 RECEIVING A BREAK CHARACTER

The Enhanced EUSART module can receive a Break character in two ways.

The first method to detect a Break character uses the FERR bit of the RCxSTA register and the received data as indicated by RCxREG. The Baud Rate Generator is assumed to have been initialized to the expected baud rate.

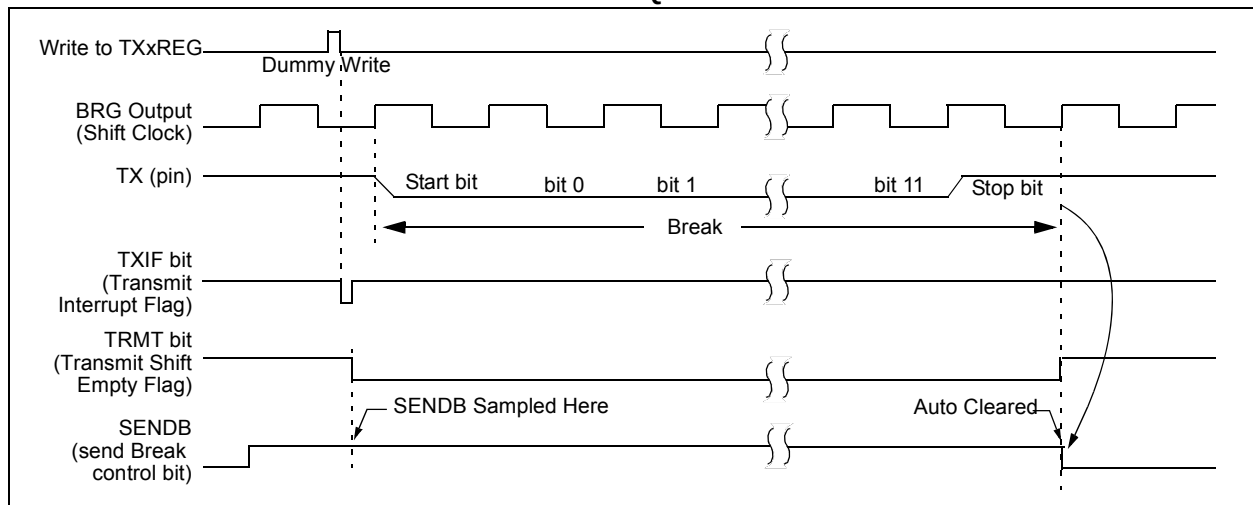
A Break character has been received when;

- RCIF bit is set
- FERR bit is set
- RCxREG = 00h

The second method uses the Auto-Wake-up feature described in **Section 25.4.3 "Auto-Wake-up on Break"**. By enabling this feature, the EUSART will sample the next two transitions on RX/DT, cause an RCIF interrupt, and receive the next data byte followed by another interrupt.

Note that following a Break character, the user will typically want to enable the Auto-Baud Detect feature. For both methods, the user can set the ABDEN bit of the BAUDxCON register before placing the EUSART in Sleep mode.

FIGURE 25-9: SEND BREAK CHARACTER SEQUENCE



25.5.2.3 EUSART Synchronous Slave Reception

The operation of the Synchronous Master and Slave modes is identical (**Section 25.5.1.5 “Synchronous Master Reception”**), with the following exceptions:

- Sleep
- CREN bit is always set, therefore the receiver is never idle
- SREN bit, which is a “don’t care” in Slave mode

A character may be received while in Sleep mode by setting the CREN bit prior to entering Sleep. Once the word is received, the RSR register will transfer the data to the RCxREG register. If the RCIE enable bit is set, the interrupt generated will wake the device from Sleep and execute the next instruction. If the GIE bit is also set, the program will branch to the interrupt vector.

25.5.2.4 Synchronous Slave Reception Set-up:

1. Set the SYNC and SPEN bits and clear the CSRC bit.
2. Clear the ANSEL bit for both the CK and DT pins (if applicable).
3. If interrupts are desired, set the RCIE bit of the PIE1 register and the GIE and PEIE bits of the INTCON register.
4. If 9-bit reception is desired, set the RX9 bit.
5. Set the CREN bit to enable reception.
6. The RCIF bit will be set when reception is complete. An interrupt will be generated if the RCIE bit was set.
7. If 9-bit mode is enabled, retrieve the Most Significant bit from the RX9D bit of the RCxSTA register.
8. Retrieve the eight Least Significant bits from the receive FIFO by reading the RCxREG register.
9. If an overrun error occurs, clear the error by either clearing the CREN bit of the RCxSTA register or by clearing the SPEN bit which resets the EUSART.

TABLE 25-10: SUMMARY OF REGISTERS ASSOCIATED WITH SYNCHRONOUS SLAVE RECEPTION

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
ANSELA	—	—	—	ANSA4	—	ANSA2	ANSA1	ANSA0	152
ANSELB ⁽¹⁾	—	—	ANSB5	ANSB4	—	—	—	—	159
ANSELC	ANSC7 ⁽¹⁾	ANSC6 ⁽¹⁾	—	—	ANSC3	ANSC2	ANSC1	ANSC0	166
BAUD1CON	ABDOVF	RCIDL	—	SCKP	BRG16	—	WUE	ABDEN	323
CKPPS	—	—	—	CKPPS<4:0>					174, 172
INTCON	GIE	PEIE	TMR0IE	INTE	IOCIE	TMR0IF	INTF	IOCIF	97
PIE1	TMR1GIE	ADIE	RCIE	TXIE	SSP1IE	CCP1IE	TMR2IE	TMR1IE	98
PIR1	TMR1GIF	ADIF	RCIF	TXIF	SSP1IF	CCP1IF	TMR2IF	TMR1IF	103
RC1REG	EUSART Receive Data Register								316*
RC1STA	SPEN	RX9	SREN	CREN	ADDEN	FERR	OERR	RX9D	322
RXPPS	—	—	—	RXPPS<4:0>					174, 172
TRISA	—	—	TRISA5	TRISA4	— ⁽²⁾	TRISA2	TRISA1	TRISA0	151
TRISB ⁽¹⁾	TRISB7	TRISB6	TRISB5	TRISB4	—	—	—	—	158
TRISC	TRISC7 ⁽¹⁾	TRISC6 ⁽¹⁾	TRISC5	TRISC4	TRISC3	TRISC2	TRISC1	TRISC0	165
TX1STA	CSRC	TX9	TXEN	SYNC	SENDB	BRGH	TRMT	TX9D	321

Legend: — = unimplemented location, read as ‘0’. Shaded cells are not used for synchronous slave reception.

* Page provides register information.

Note 1: PIC16(L)F1618 only.

2: Unimplemented, read as ‘1’.

26.2 Compare Mode

The Compare mode function described in this section is available and identical for all CCP modules.

Compare mode makes use of the 16-bit Timer1 resource. The 16-bit value of the CCPRxH:CCPRxL register pair is constantly compared against the 16-bit value of the TMR1H:TMR1L register pair. When a match occurs, one of the following events can occur:

- Toggle the CCPx output
- Set the CCPx output
- Clear the CCPx output
- Pulse the CCPx output
- Generate a Software Interrupt
- Optionally Reset TMR1

The action on the pin is based on the value of the MODE<3:0> control bits of the CCPxCON register. At the same time, the interrupt flag CCPxIF bit is set.

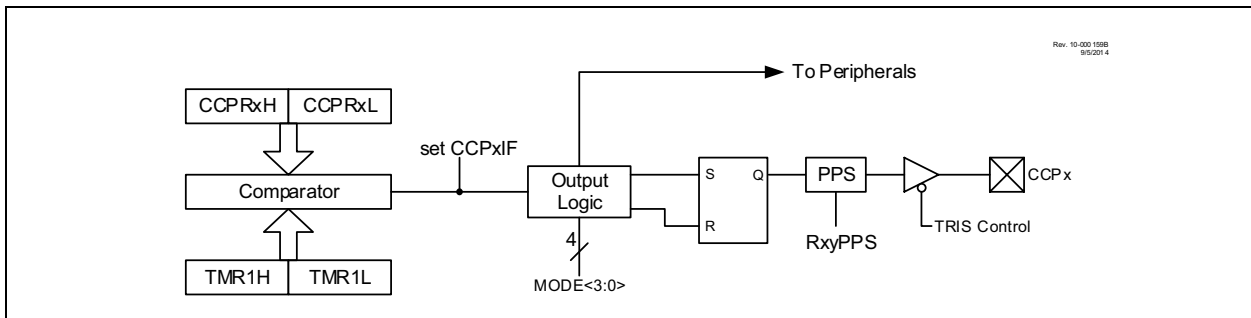
All Compare modes can generate an interrupt.

Figure 26-2 shows a simplified diagram of the compare operation.

26.2.1 CCPx PIN CONFIGURATION

The user must configure the CCPx pin as an output by clearing the associated TRIS bit.

FIGURE 26-2: COMPARE MODE OPERATION BLOCK DIAGRAM



REGISTER 26-2: CCPTMRS: PWM TIMER SELECTION CONTROL REGISTER 0

R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0
P4TSEL<1:0>		P3TSEL<1:0>		C2TSEL<1:0>		C1TSEL<1:0>	
bit 7							bit 0

Legend:

R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-6	P4TSEL<1:0>: PWM4 Timer Selection bits
	11 = Reserved
	10 = PWM4 is based off Timer6 in PWM mode
	01 = PWM4 is based off Timer4 in PWM mode
	00 = PWM4 is based off Timer2 in PWM mode
bit 5-4	P3TSEL<1:0>: PWM3 Timer Selection bits
	11 = Reserved
	10 = PWM3 is based off Timer6 in PWM mode
	01 = PWM3 is based off Timer4 in PWM mode
	00 = PWM3 is based off Timer2 in PWM mode
bit 3-2	C2TSEL<1:0>: CCP2 (PWM2) Timer Selection bits
	11 = Reserved
	10 = CCP2 is based off Timer6 in PWM mode
	01 = CCP2 is based off Timer4 in PWM mode
	00 = CCP2 is based off Timer2 in PWM mode
bit 1-0	C1TSEL<1:0>: CCP1 (PWM1) Timer Selection bits
	11 = Reserved
	10 = CCP1 is based off Timer6 in PWM mode
	01 = CCP1 is based off Timer4 in PWM mode
	00 = CCP1 is based off Timer2 in PWM mode

30.6.10 GATED COUNTER MODE

This mode counts pulses on the SMTx_signal input, gated by the SMTxWIN input. It begins incrementing the timer upon seeing a rising edge of the SMTxWIN input and updates the SMTxCPW register upon a falling edge on the SMTxWIN input. See Figure 30-19 and Figure 30-20.

REGISTER 30-9: SMTxTMRL: SMT TIMER REGISTER – LOW BYTE

R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0
SMTxTMR<7:0>							
bit 7				bit 0			

Legend:

R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-0 **SMTxTMR<7:0>**: Significant bits of the SMT Counter – Low Byte

REGISTER 30-10: SMTxTMRH: SMT TIMER REGISTER – HIGH BYTE

R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0
SMTxTMR<15:8>							
bit 7				bit 0			

Legend:

R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-0 **SMTxTMR<15:8>**: Significant bits of the SMT Counter – High Byte

REGISTER 30-11: SMTxTMRU: SMT TIMER REGISTER – UPPER BYTE

R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0
SMTxTMR<23:16>							
bit 7				bit 0			

Legend:

R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-0 **SMTxTMR<23:16>**: Significant bits of the SMT Counter – Upper Byte

TABLE 31-2: SUMMARY OF REGISTERS ASSOCIATED WITH THE ANGULAR TIMER MODULE

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on page
AT1CC1H	—	—	—	—	—	—	CC1<9:8>		475
AT1CC1L	CC1<7:0>								475
AT1CCON1	CC1EN	—	—	CC1POL	CAP1P	—	—	CC1MODE	473
AT1CCON2	CC2EN	—	—	CC2POL	CAP2P	—	—	CC2MODE	473
AT1CCON3	CC3EN	—	—	CC3POL	CAP3P	—	—	CC3MODE	473
AT1CLK	—	—	—	—	—	—	—	CS0	463
AT1CON0	EN	PREC	PS<1:0>		POL	—	APMOD	MODE	461
AT1CON1	—	PHP	—	PRP	—	MPP	ACCS	VALID	462
AT1CSEL1	—	—	—	—	—	CP1S<2:0>			474
AT1CSEL2	—	—	—	—	—	CP2S<2:0>			474
AT1CSEL3	—	—	—	—	—	CP3S<2:0>			474
AT1ERRH	ERR<15:8>								472
AT1ERRL	ERR<7:0>								472
AT1IE0	—	—	—	—	—	PHSIE	MISSIE	PERIE	468
AT1IR0	—	—	—	—	—	PHSIF	MISSIF	PERIF	468
AT1IE1	—	—	—	—	—	CC3IE	CC2IE	CC1IE	469
AT1IR1	—	—	—	—	—	CC3IF	CC2IF	CC1IF	470
AT1MISSH	MISS<15:8>								465
AT1MISSL	MISS<7:0>								465
AT1PERH	POV	PER<14:8>							466
AT1PERL	PER<7:0>								466
AT1PHSH	—	—	—	—	—	—	PHS<9:8>		467
AT1PHSL	PHS<7:0>								467
AT1RESH	—	—	—	—	—	—	RES<9:8>		464
AT1RESL	RES<7:0>								464
AT1SIG	—	—	—	—	—	SSEL<2:0>			463
AT1STPTH	—	STPT<14:8>							471
AT1STPTL	STPT<7:0>								471
PIE5	TMR3GIE	TMR3IE	TMR5GIE	TMR5IE	—	AT1IE	PID1EIE	PID1DIE	102
PIR5	TMR3GIF	TMR3IF	TMR5GIF	TMR5IF	—	AT1IF	PID1EIF	PID1DIF	107

Legend: — = unimplemented, read as '0'. Shaded cells are unused by the AT module.

37.2 MPLAB XC Compilers

The MPLAB XC Compilers are complete ANSI C compilers for all of Microchip's 8, 16, and 32-bit MCU and DSC devices. These compilers provide powerful integration capabilities, superior code optimization and ease of use. MPLAB XC Compilers run on Windows, Linux or MAC OS X.

For easy source level debugging, the compilers provide debug information that is optimized to the MPLAB X IDE.

The free MPLAB XC Compiler editions support all devices and commands, with no time or memory restrictions, and offer sufficient code optimization for most applications.

MPLAB XC Compilers include an assembler, linker and utilities. The assembler generates relocatable object files that can then be archived or linked with other relocatable object files and archives to create an executable file. MPLAB XC Compiler uses the assembler to produce its object file. Notable features of the assembler include:

- Support for the entire device instruction set
- Support for fixed-point and floating-point data
- Command-line interface
- Rich directive set
- Flexible macro language
- MPLAB X IDE compatibility

37.3 MPASM Assembler

The MPASM Assembler is a full-featured, universal macro assembler for PIC10/12/16/18 MCUs.

The MPASM Assembler generates relocatable object files for the MPLINK Object Linker, Intel® standard HEX files, MAP files to detail memory usage and symbol reference, absolute LST files that contain source lines and generated machine code, and COFF files for debugging.

The MPASM Assembler features include:

- Integration into MPLAB X IDE projects
- User-defined macros to streamline assembly code
- Conditional assembly for multipurpose source files
- Directives that allow complete control over the assembly process

37.4 MPLINK Object Linker/ MPLIB Object Librarian

The MPLINK Object Linker combines relocatable objects created by the MPASM Assembler. It can link relocatable objects from precompiled libraries, using directives from a linker script.

The MPLIB Object Librarian manages the creation and modification of library files of precompiled code. When a routine from a library is called from a source file, only the modules that contain that routine will be linked in with the application. This allows large libraries to be used efficiently in many different applications.

The object linker/library features include:

- Efficient linking of single libraries instead of many smaller files
- Enhanced code maintainability by grouping related modules together
- Flexible creation of libraries with easy module listing, replacement, deletion and extraction

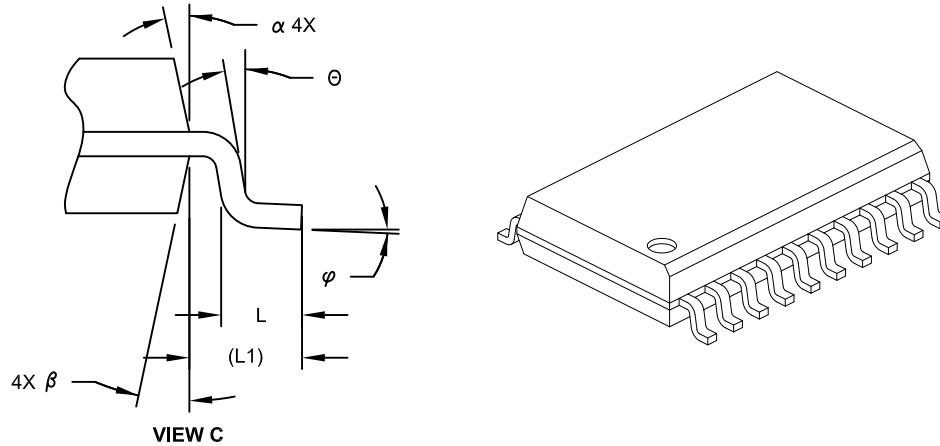
37.5 MPLAB Assembler, Linker and Librarian for Various Device Families

MPLAB Assembler produces relocatable machine code from symbolic assembly language for PIC24, PIC32 and dsPIC DSC devices. MPLAB XC Compiler uses the assembler to produce its object file. The assembler generates relocatable object files that can then be archived or linked with other relocatable object files and archives to create an executable file. Notable features of the assembler include:

- Support for the entire device instruction set
- Support for fixed-point and floating-point data
- Command-line interface
- Rich directive set
- Flexible macro language
- MPLAB X IDE compatibility

20-Lead Plastic Small Outline (SO) - Wide, 7.50 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N	20		
Pitch	e	1.27 BSC		
Overall Height	A	-	-	2.65
Molded Package Thickness	A2	2.05	-	-
Standoff §	A1	0.10	-	0.30
Overall Width	E	10.30 BSC		
Molded Package Width	E1	7.50 BSC		
Overall Length	D	12.80 BSC		
Chamfer (Optional)	h	0.25	-	0.75
Foot Length	L	0.40	-	1.27
Footprint	L1	1.40 REF		
Lead Angle	Θ	0°	-	-
Foot Angle	φ	0°	-	8°
Lead Thickness	c	0.20	-	0.33
Lead Width	b	0.31	-	0.51
Mold Draft Angle Top	α	5°	-	15°
Mold Draft Angle Bottom	β	5°	-	15°

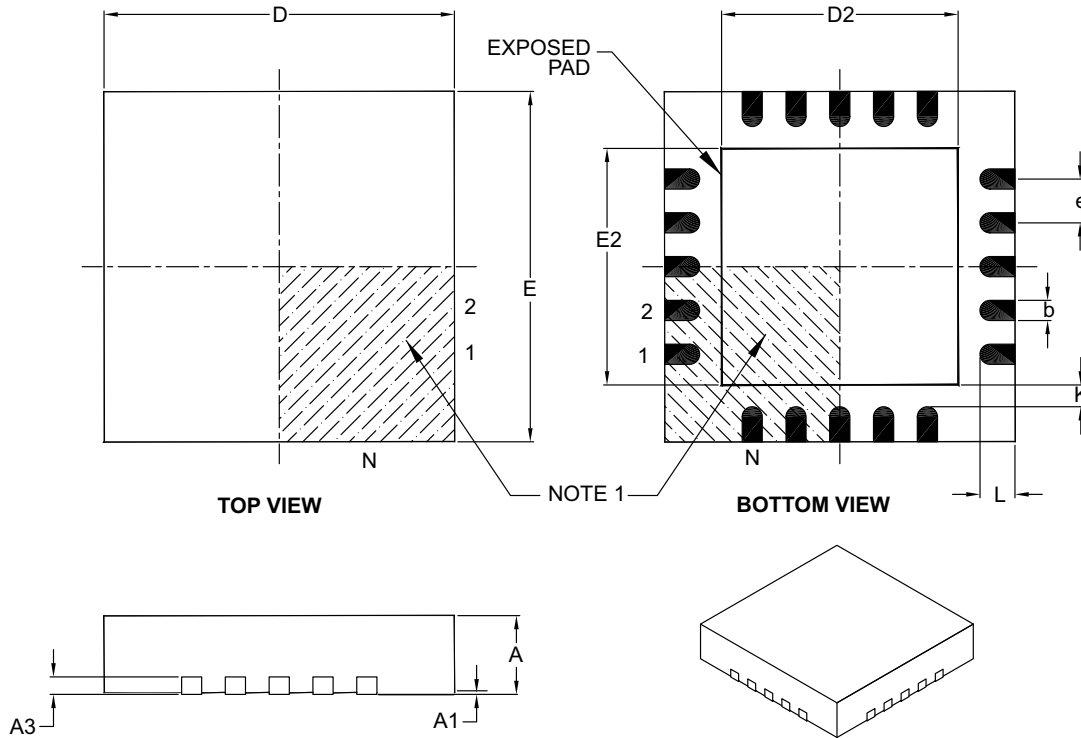
Notes:

- Pin 1 visual index feature may vary, but must be located within the hatched area.
- § Significant Characteristic
- Dimension D does not include mold flash, protrusions or gate burrs, which shall not exceed 0.15 mm per end. Dimension E1 does not include interlead flash or protrusion, which shall not exceed 0.25 mm per side.
- Dimensioning and tolerancing per ASME Y14.5M
 - BSC: Basic Dimension. Theoretically exact value shown without tolerances.
 - REF: Reference Dimension, usually without tolerance, for information purposes only.
- Datums A & B to be determined at Datum H.

Microchip Technology Drawing No. C04-094C Sheet 2 of 2

20-Lead Plastic Quad Flat, No Lead Package (ML) – 4x4x0.9 mm Body [QFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N	20		
Pitch	e	0.50 BSC		
Overall Height	A	0.80	0.90	1.00
Standoff	A1	0.00	0.02	0.05
Contact Thickness	A3	0.20 REF		
Overall Width	E	4.00 BSC		
Exposed Pad Width	E2	2.60	2.70	2.80
Overall Length	D	4.00 BSC		
Exposed Pad Length	D2	2.60	2.70	2.80
Contact Width	b	0.18	0.25	0.30
Contact Length	L	0.30	0.40	0.50
Contact-to-Exposed Pad	K	0.20	—	—

Notes:

- Pin 1 visual index feature may vary, but must be located within the hatched area.
- Package is saw singulated.
- Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-126B